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I wish all of you health and happiness.

That statement brought great comfort to my brother and I am glad for that.

So this is hard, real hard.

If you like my buttons, please visit Cheapskate Designs! Please keep the people in Haiti & Chili in your prayers.

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bought this tube at CVS (a drugstore) for 50% off and she had no idea

I am deeply grateful for all you have done.

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